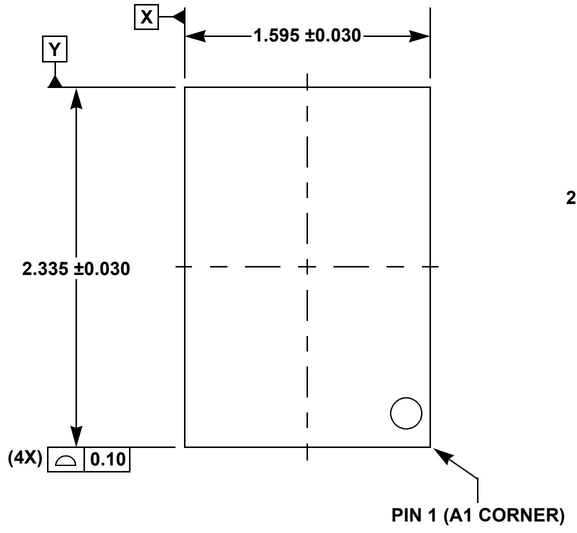
Package Outline Drawing

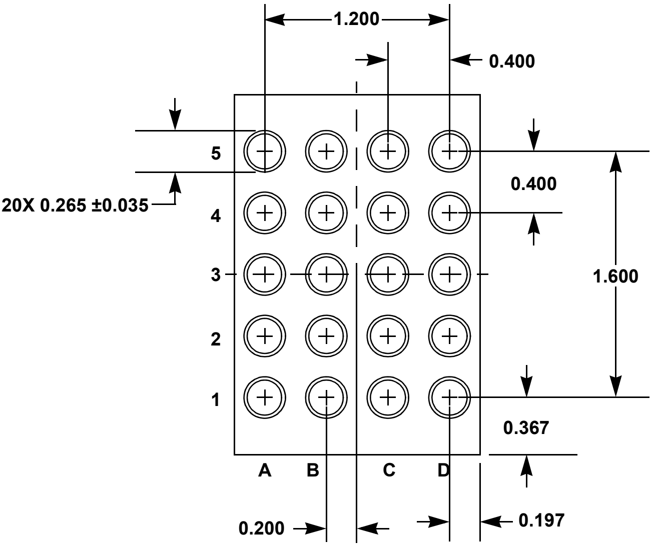
W4x5.20S

20 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP)

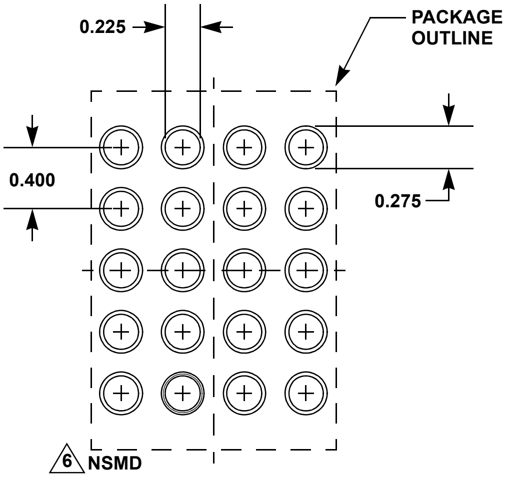
Rev 0, 12/16



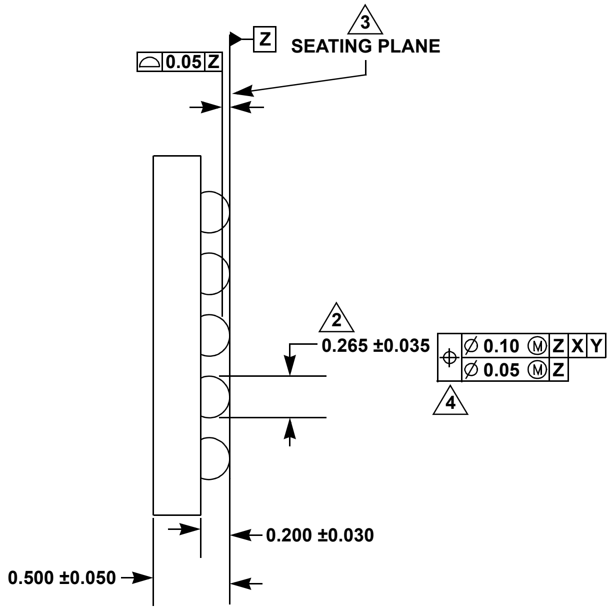
TOP VIEW



BOTTOM VIEW



TYPICAL RECOMMENDED LAND PATTERN



SIDE VIEW

NOTES:

1. Dimensions and tolerance per ASME Y 14.5M - 1994.

△2. Dimension is measured at the maximum bump diameter parallel to primary datum Z.

△3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.

△4. Bump position designation per JESD 95-1, SPP-010.

5. All dimensions are in millimeters.

△6. NSMD refers to non-solder mask defined pad design per Intersil Techbrief www.intersil.com/content/dam/Intersil/documents/tb45/tb451.pdf